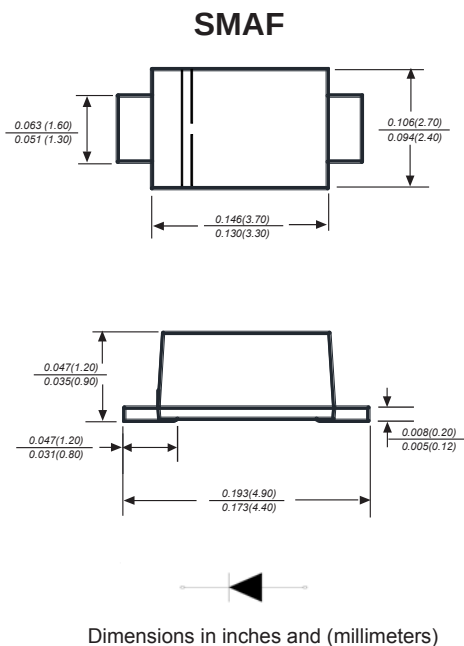


Features

1. The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
2. For surface mounted applications
3. Metal silicon junction, majority carrier conduction
4. Low power loss, high efficiency
5. Built-in strain relief, ideal for automated placement
6. High forward surge current capability
7. High temperature soldering guaranteed:
260 °C/10 seconds at terminals

Mechanical Data

Case : JEDEC SMAF molded plastic body
Terminals : Solderable per MIL-STD-750, Method 2026
Polarity : Color band denotes cathode end
Mounting Position : Any
Weight : 0.0018 ounce, 0.064 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

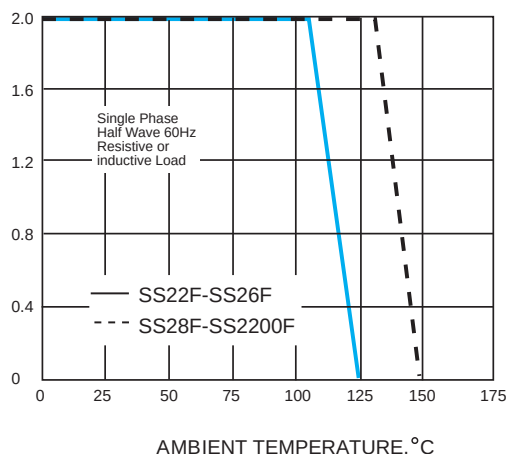
Parameter	SYMBOLS	SS22F	SS23F	SS24F	SS25F	SS26F	SS28F	SS210F	SS2150F	SS2200F	UNITS
Marking Code		SS22F	SS23F	SS24F	SS25F	SS26F	SS28F	SS210F	SS2150F	SS2200F	
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at TL(see fig.1)	I _(AV)	2.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50									A
Maximum instantaneous forward voltage at 2.0A	V _F	0.55			0.70		0.85			0.95	V
Maximum DC reverse current T _A =25℃ at rated DC blocking voltage T _A =125℃	I _R	0.5						0.2		mA	
		10.0				5.0		2.0			
Typical junction capacitance (NOTE 1)	C _J	220			180						pF
Typical thermal resistance (NOTE 2)	R _{θJA}	75.0									℃/W
Operating junction temperature range	T _J	- 5 0 t o + 1 2 5					- 5 0 t o + 1 5 0				℃
Storage temperature range	T _{STG}	- 5 0 t o + 1 5 0									℃

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Typical Characteristics

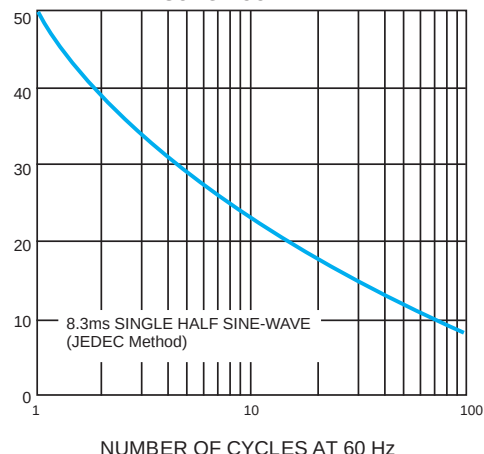
AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



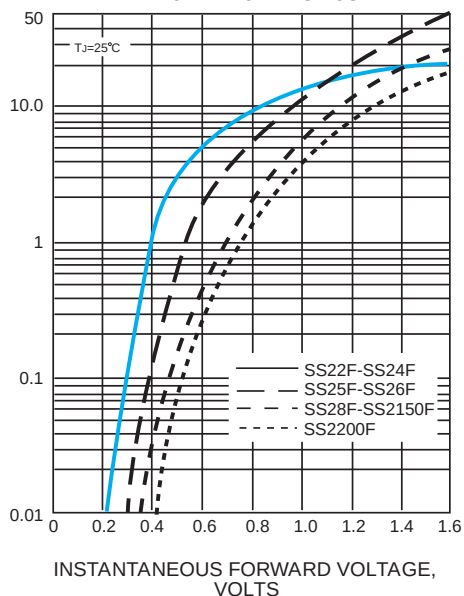
PEAK FORWARD SURGE CURRENT,
AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



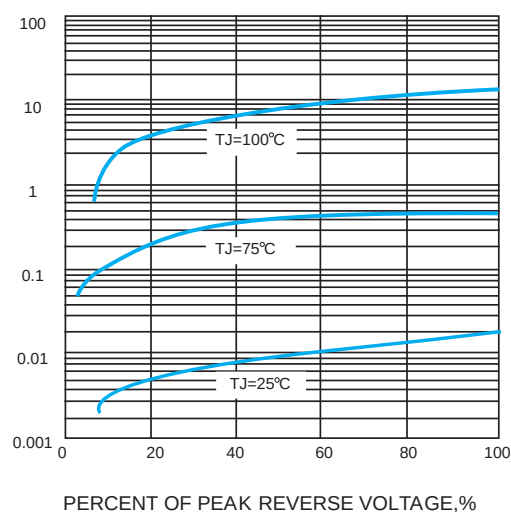
INSTANTANEOUS FORWARD
CURRENT,AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



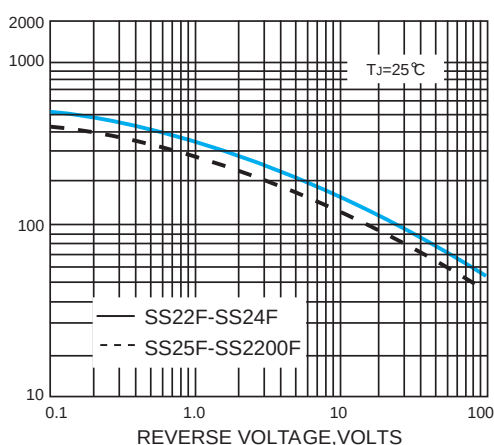
INSTANTANEOUS REVERSE CURRENT,
MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



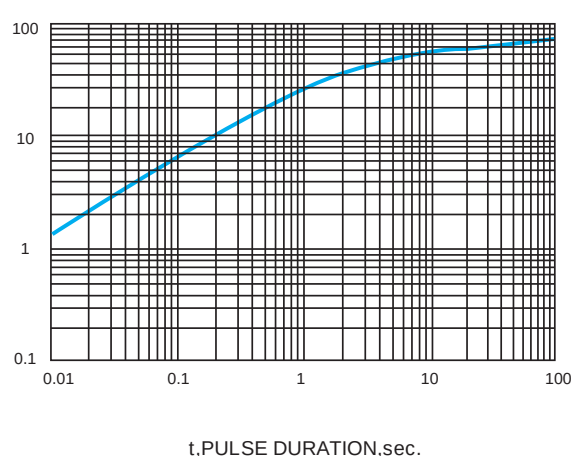
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE

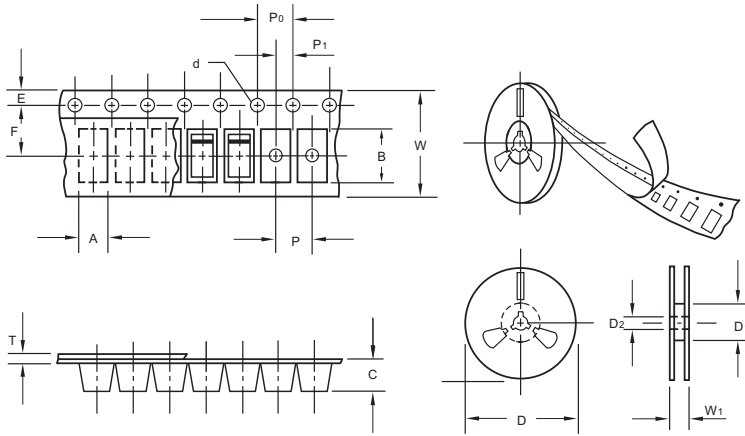


TRANSIENT THERMAL IMPEDANCE,
°C/W

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



Packing information



unit:mm

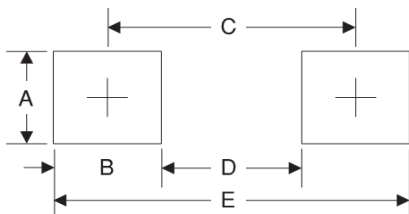
Item	Symbol	Tolerance	SMAF
Carrier width	A	0.1	2.80
Carrier length	B	0.1	4.75
Carrier depth	C	0.1	1.42
Sprocket hole	d	0.05	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	54.40
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.05
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	8.00
Reel width	W1	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMAF	7"	3,000	4.0	6,000	210*208*203	178	400*265*400	120,000	10.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.8	0.071
B	1.6	0.063
C	3.8	0.150
D	2.2	0.087
E	5.4	0.213